1.

Record Nr.	UNINA9910557344603321
Autore	Amengual Mark
Titolo	Exploring Cross-linguistic Effects and Phonetic Interactions in the Context of Bilingualism
Pubbl/distr/stampa	Basel, Switzerland, : MDPI - Multidisciplinary Digital Publishing Institute, 2021
Descrizione fisica	1 online resource (380 p.)
Soggetti	Language and Linguistics
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Sommario/riassunto	This Special Issue includes fifteen original state-of-the-art research articles from leading scholars that examine cross-linguistic influence in bilingual speech. These experimental studies contribute to the growing number of studies on multilingual phonetics and phonology by introducing novel empirical data collection techniques, sophisticated methodologies, and acoustic analyses, while also presenting findings that provide robust theoretical implications to a variety of subfields, such as L2 acquisition, L3 acquisition, laboratory phonology, acoustic phonetics, psycholinguistics, sociophonetics, blingualism, and language contact. These studies in this book further elucidate the nature of phonetic interactions in the context of bilingualism and multilingualism and outline future directions in multilingual phonetics and phonology research.

2.

Record Nr.	UNINA9910557401503321
Autore	Górecki Krzysztof
Titolo	Latest Advances in Electrothermal Models
Pubbl/distr/stampa	Basel, Switzerland, : MDPI - Multidisciplinary Digital Publishing Institute, 2021
Descrizione fisica	1 online resource (140 p.)
Soggetti	History of engineering and technology
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Sommario/riassunto	This book is devoted to the latest advances in the area of electrothermal modelling of electronic components and networks. It contains eight sections by different teams of authors. These sections contain the results of: (a) electro-thermal simulations of SiC power MOSFETs using a SPICE-like simulation program; (b) modelling thermal properties of inductors taking into account the influence of the core volume on the efficiency of heat removal; (c) investigations into the problem of inserting a temperature sensor in the neighbourhood of a chip to monitor its junction temperature; (d) computations of the internal temperature of power LEDs situated in modules containing multiple-power LEDs, taking into account both self-heating in each power LED and mutual thermal couplings between each diode; (e) analyses of DC-DC converters using the electrothermal averaged model of the diode-transistor switch, including an IGBT and a rapid-switching diode; (f) electrothermal modelling of SiC power BJTs; (g) analysis of the efficiency of selected algorithms used for solving heat transfer problems at nanoscale; (h) analysis related to thermal simulation of the test structure dedicated to heat-diffusion investigation at the nanoscale.